



AMD CrossFire™ Series Chipset

Packaging and Branding Guidelines

Introduction

Your Guide to Consistent Marketing and Packaging Guidelines

These guidelines are intended to assist you in creating powerful marketing for your products that use the newly rebranded AMD CrossFire™ Series chipset products. By using these guidelines you will generate greater interest in your products and affinity with your audiences.

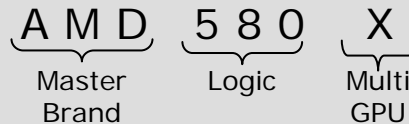
The following pages offer resources and guidelines for creating compelling packaging and marketing materials that effectively align with CrossFire.

Please use this guide to benefit from the value of the AMD brand and expand the reach of your marketing dollars.

Summary of All Products Belonging to the AMD CrossFire™ Series Chipset

The list below summarizes the CrossFire™ Chipset product offering for the AMD platform

ASIC Variant	Platform	BRAND NAMES
		Chipset
RD480	DT	AMD 480X
RD550	DT	AMD 550X
RD580	DT	AMD 580X



Section 1

Logos and Text Treatment

Logos and Text Treatment

Logos and text treatments lend brand value to your marketing and packaging. By including these graphic elements in your packaging, you create immediate awareness and connection with your audience.

This guide outlines the proper usage of all AMD Chipset logos.

All logos must be used as is and cannot be altered in any way.

If there are any questions regarding these logo or brand identity guidelines, please contact your regional partner marketing manager.

Logos and Text Treatment

AMD should be in full caps. All AMD Chipset and product feature names should be spelled out in lower case with the first letter capitalized. Do not spell the entire product or product feature name in capital letters only. For 'CrossFire', 'C' and 'F' are in capital letters and should be followed by "TM".

Correct Examples	Incorrect Examples
AMD 580X CrossFire™ Chipset	AMD 480X CROSSFIRE™ Chipset
AMD 580X CrossFire™ Chipset	Amd 480X Crossfire™ Chipset
AMD 580X CrossFire™ Chipset	AMD 480X CrossFire Chipset

Note: ASIC variant name (i.e R580) is **NOT** to be used at anytime.

Logos and Text Treatment

Use of trademark “™” and “®”

COPY

In all copy, the applicable trademark notice must be used beside all product and product feature names used in: (i) all headlines; and (ii) the first use of the product or product feature name in the text.

PACKAGING

The applicable trademark notice must be used beside all product names prominently featured (greater than 2X text size) on the packaging. For all packaging copy, the applicable trademark notice must be used beside the first instance of use of all product and product feature names used in the text.

NOTICE SYMBOL

Registered marks should be followed by the “®” notice symbol. All other product and product feature names for which AMD is claiming trademark rights or for which AMD has filed a trademark application should be followed by the “™” notice symbol. Please check with the Chipset Marketing Department to ensure you are using the correct notice symbol.

Logos and Text Treatment

Using AMD CrossFire Chipset Logos

Use AMD CrossFire Chipset logos when promoting motherboards or systems with these chipset.

The logos must be used in the following applications:

- On the heat sink for Northbridge. (Logo on the Southbridge is optional)
- On the PC boot up screen (BIOS Splash)
- On retail packaging
- Advertising and promotional material (print and online)

Logos and Text Treatment

This logo is used on the Northbridge and or Southbridge on the Motherboard heat sink



File name: `_HS.eps`



These logos are used on the PC boot up Screen (BIOS Splash), for motherboard packaging (see packaging guidelines for more details), advertisement, collateral material etc.



Logo Use

File name:

Splash Screen

`_BIOS.bmp`

Print/Package

`_PRINT.eps`

Web/Electronic

`_GP`

Logos and Text Treatment

Requirements for BIOS Splash Screen Logo

The BIOS Splash screen logo must be placed either in the center of the monitor or the upper top left-hand corner of the screen

The logo must be no smaller than 2 inches in width (length to be proportional)

The logo must be present for a minimum of 2 seconds



Section 2

Packaging Guidelines

Packaging Guidelines

These packaging standards have been developed to provide consistent brand recognition for the logo established for all AMD products, and to more clearly communicate the consumer benefits of AMD products.

Please follow these guidelines for all motherboard packaging with the AMD CrossFire chipset product line.

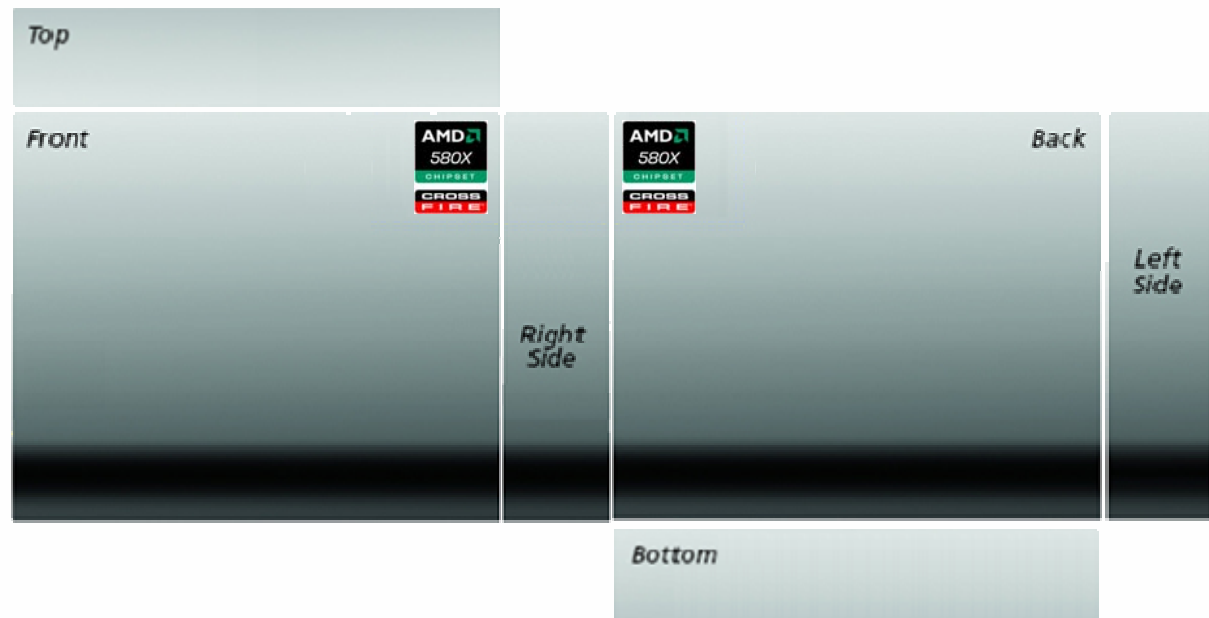
Packaging Guidelines

Mandatory Box Layout Requirements:

There is only one mandatory element for all partner packaging:

The AMD CrossFire Chipset product logo MUST be on the front and back panels of the retail box.

This elements must be reproduced without variation in the positions identified. Partner artwork can then be placed in the grey zones of the marked illustration below.



Packaging Guidelines

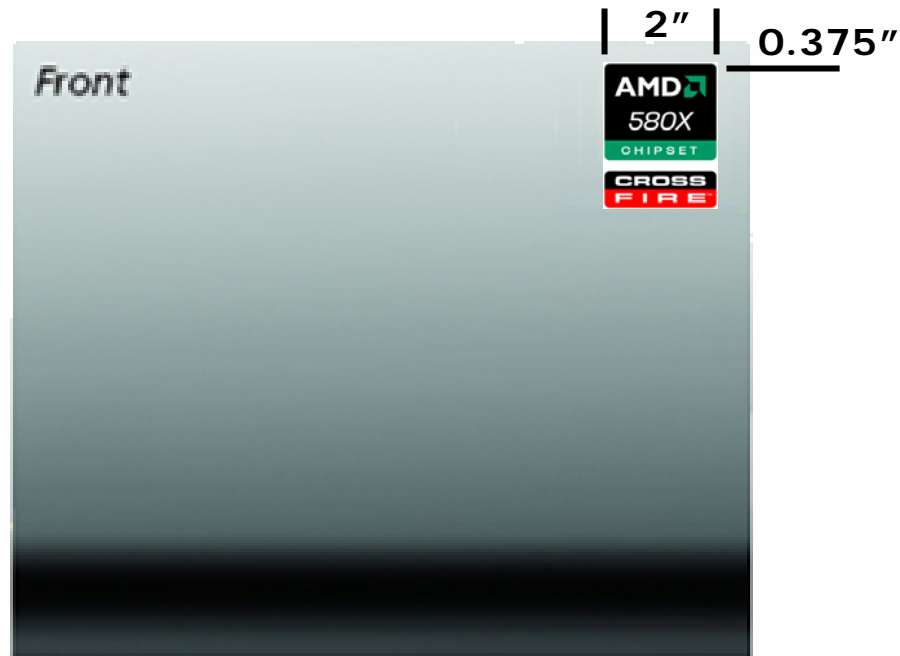
Other Mandatory Requirements:

1. The proportion of logo size to package area shown must be maintained (see below)
2. To ensure sufficient visibility, an unobstructed area should surround the Chipset badge logo.
3. The TM should be placed after CrossFire. The TM must always appear at least once.
4. Pantone color 347 is always used for AMD green. Pantone color 185 is always used for CrossFire red.
5. Partners must include the following standard legal line on all packaging or other advertising materials which utilize any AMD logos or visual identities:
"AMD, the AMD Arrow logo, ATI, CrossFire, Radeon, and combinations thereof are trademarks of Advanced Micro Devices, Inc. Other names are for informational purposes only and may be trademarks of their respective owners."

Packaging Guidelines

Logo Sizing Requirements

1. Logo must be 0.375" away from box edge and other logos.
2. The logo must be at least 2" wide.



Packaging Guidelines

Incorrect Use of Chipset Package Art Template

1. The chipset badge logo is not placed on the front/top side of the packaging
2. The badge is too small, not meeting the 2" wide criteria
3. Partners may not add unauthorized numeric or alphabetical extensions after the Chipset technology brand name. e.g. AMD 580X Pro Lite etc.
4. The Chipset badge cannot be placed in alternative locations on a partner pack

